

AMENDMENTS TO THE CLAIMS

Claim 1 (currently amended): A wafer processing system comprising:
a ~~load-lock~~ load lock having only one pedestal configured to support a single wafer thereon during a pump down of the load lock, the ~~load-lock~~ load lock having an integral cooling unit for cooling the single wafer;
a transport module having a load chamber, a transfer chamber, and a pass-through chamber located between the load chamber and the transfer chamber, the load chamber being coupled to the load lock;
an intermediate process module coupled to the load chamber and the transfer chamber;
a loader configured to receive a plurality of wafers to be processed;
a robot configured to transfer a wafer between the load lock and the loader, the robot being exposed to atmosphere;
a first set of process modules coupled to the load chamber; and
a second set of process modules coupled to the transfer chamber.

Claim 2 (original): The system of claim 1 wherein a process module in the first set of process modules includes a pre-clean module.

Claim 3 (original): The system of claim 1 wherein a process module in the first set of process modules includes a physical vapor deposition module.

Claim 4 (original): The system of claim 1 wherein a process module in the first set of process modules includes a chemical vapor deposition module.

Claim 5 (original): The system of claim 1 wherein a process module in the second set of process modules includes a pre-clean module.

Claim 6 (original): The system of claim 1 wherein a process module in the second set of process modules includes a chemical vapor deposition module.

Claim 7 (original): The system of claim 1 wherein a process module in the second set of process modules includes a physical vapor deposition module.

Claim 8 (cancelled)

Claim 9 (original): The system of claim 1 wherein the intermediate process module is configured as a degas module.

Claim 10 (original): The system of claim 1 wherein the pass-through chamber is configured as a cooling station.

Claim 11 (original): The system of claim 1 wherein the intermediate process module is configured as a pre-clean module.

Claim 12 (original): The system of claim 1 wherein the intermediate process module is configured as a PVD module.

Claim 13 (original): The system of claim 1 wherein the intermediate process module is configured as a CVD module.

Claims 14-16 (cancelled)

Claim 17 (currently amended) A wafer processing system comprising:

a load lock having only one pedestal for supporting a wafer thereon during a pump down of the load lock, the pedestal having an integral cooling unit for cooling a wafer;

a transport module having a first chamber, a second chamber, and a pass-through chamber between the first chamber and the second chamber, the first chamber being coupled to the load lock;

a loader configured to receive a plurality of wafers to be processed;

a robot configured to transfer a wafer between the load lock and the loader, the robot being exposed to atmosphere;

an intermediate process module coupled to the first chamber;

a process module coupled to the first chamber; and

another process module coupled to the second chamber.

Claim 18 (cancelled)

Claim 19 (previously presented): The system of claim 17 wherein the pedestal is water-cooled.

Claim 20 (original): The system of claim 17 wherein the intermediate process module is also coupled to the second chamber.

Claim 21 (original): The system of claim 17 wherein the pass-through chamber is configured as a cooling station.

Claims 22-24 (cancelled)